

02/33/06

101308283

To the	Honorable Commissioner of Patents and Trademarks. Please record the	attached original documents or copy thereof.			
To the Honorable Commissioner of Patents and Trademarks. Please record the 1. Name of conveying party (ies): Buford H. Carter, Jr. Dennis D. Davis David R. Kee Richard E. Johnson		2. Name and Address of receiving party(ies): Name: Texas Instruments Incorporated Address: P.O. Box 655474 M/S 3999 City: Dallas State: TX Zip: 75265			
Additi	onal name(s) attached?Yes_X_No	Additional name(s) attached?YesX_No			
3.	Nature of Conveyance:				
	x Assignment Merger Security Agreement Change of Name				
	Other				
	Execution Date: March 2, 1999 and March 4, 1999				
4.	Application number(s) or patent number(s).				
	\underline{x} This document is being filed together with a new application.				
	Execution date of the application: March 2, 1999 and March 4, 1999				
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OF F	INTEGRATED CIRCUIT DEVICE WITH DEPRESS FABRICATION.	SIONS FOR RECEIVING SOLDER BALLS AND MET			
OF F	INTEGRATED CIRCUIT DEVICE WITH DEPRESS FABRICATION. scket No.: TI-28585	SIONS FOR RECEIVING SOLDER BALLS AND MET			
OF F	INTEGRATED CIRCUIT DEVICE WITH DEPRESS FABRICATION. Scket No.: TI-28585 Patent Application No.(s) Additional numbers attached? Yesx No Name and address of party to whom correspondence concerning	B. Patent No.(s)			
Dos A.	INTEGRATED CIRCUIT DEVICE WITH DEPRESS FABRICATION. Scket No.: TI-28585 Patent Application No.(s) Additional numbers attached?YesxNo Name and address of party to whom correspondence concerning document should be mailed:	B. Patent No.(s) Additional numbers attached? Yes x No			
Dos A.	INTEGRATED CIRCUIT DEVICE WITH DEPRESS FABRICATION. Seket No.: TI-28585 Patent Application No.(s) Additional numbers attached?YesxNo Name and address of party to whom correspondence concerning document should be mailed: Name: Gary C. Honeycutt Navarro IP Law Group, P.C. 801 E. Campbell Rd. Suite 655	B. Patent No.(s) Additional numbers attached? Yes x No 6. Number of applications and patents involved:			
Dos A.	INTEGRATED CIRCUIT DEVICE WITH DEPRESS FABRICATION. Ocket No.: TI-28585 Patent Application No.(s) Additional numbers attached? Yes x No Name and address of party to whom correspondence concerning document should be mailed: Name: Gary C. Honeycutt Navarro IP Law Group, P.C.	B. Patent No.(s) Additional numbers attached? Yes x No 6. Number of applications and patents involved: 1 7. Amount of fee enclosed or authorized to be charged: \$40			
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PATENT REEL: 010653 FRAME: 0218

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 7839 Churchill Way, MS 3999, Dallas, Texas 75251, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	Integrated Circuit Device with Depressions for Receiving Solder Balls and Method of Fabrication		
SIGNATURE OF INVENTOR AND NAME	Berfo-RH Cates J.	Dennis D. Davis	David R. Kee
DATE OF SIGNATURE	3-2-99	3-2-99	3/2/99
RESIDENCE (City, County, State)	Richardson, Dallas County, Texas	Garland, Dallas County, Texas	Richardson, Dallas County, Texas
DATE AFPLICATION EXECUTED	3-2-99	3-2-99	3/2/99

After recording Assignment, please return to:

Gary C. Honeycutt
Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265

PATENT REEL: 010653 FRAME: 0219

ATTOPNEY	DOCKET	NO.				
TI-28585						

ASSIGNMENT

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION		cuit Device with Depressions for Receiving r Balls and Method of Fabrication	
SIGNATURE OF INVENTOR AND NAME	Richard E. Johnson	N/A	N/A
DATE OF SIGNATURE	3-4-99		
RESIDENCE (City, County, State)	Flower Mound, Denton County, Texas		
DATE AFPLICATION EXECUTED	3-4-99		

After recording Assignment, please return to:
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Dallas, TX 75265

RECORDED: 02/23/2000

PATENT REEL: 010653 FRAME: 0220